

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	2.80mil		
4	Dielectric 1	FR-4	14.00mil	4.2	
5	Signal Layer 1	Copper	1.42mil		
6	Dielectric 3		24.00mil	4.2	
7	Signal Layer 2	Copper	2.80mil		
8	Dielectric 2		14.00mil	4.2	
9	Bottom Layer	Copper	2.80mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 _ML
 MIN. CLEARANCE: 0.2 mm
 MIN. VIA PAD SIZE: 10 _ML
 MINIMUM ANNULAR RING 0.05mm (2ML) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- 5 _ML, HOLES +/- 3 _ML

MATERIAL:
 FR-408 FR-4 High Tg OTHER _____
 THICKNESS: 62 MIL (1.6mm) +/-10% OTHER _____
 TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____
 BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

DRILLING:
 REFERENCE: AS SHOWN NC_DRILL FILES
 PTH MIN COPPER THICKNESS: 1MIL OTHER _____

BOARD FINISH:
 SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER _____
 SOLDER RESIST COLOR:
 GREEN BLUE OTHER _____

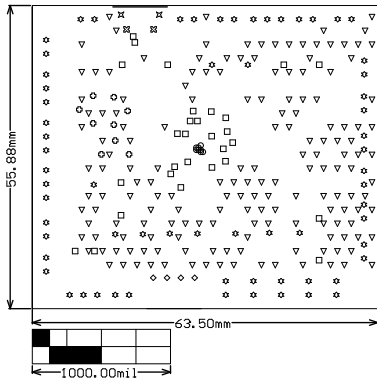
SURFACE FINISH: IMMERSION GOLD (ENIG) ENERP
 IMM. TIN/SILVER OR EQUIV OTHER _____

ARRAY/PANEL: CUT AND TRM PER MECH LAYER 1
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:
 ANSI IPC-A-600F CLASS -> 1 2 3
 UL 94V-0 RoHS OTHER PER ORDER

ADDITIONAL REQUIREMENTS:
 MICROSECTION: YES
 BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER
 MANUFACTURER'S UL: RAL METAL SLK

Symbol	Quantity	Finished Hole Size	Plated	Hole Type
□	8	6.00mil (0.152mm)	PTH	Round
☆	167	10.00mil (0.254mm)	PTH	Round
▽	25	12.00mil (0.305mm)	PTH	Round
○	9	20.00mil (0.508mm)	PTH	Round
▽	2	33.46mil (0.850mm)	PTH	Round
⊗	65	40.00mil (1.016mm)	PTH	Round
○	4	40.16mil (1.020mm)	PTH	Round
◇	4	63.00mil (1.600mm)	PTH	Round
■	2	23.62mil (0.600mm)	PTH	Slot
	286 Total			



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR731	REV: A	SUN REV: Not In Version Control
LAYER NAME = 060054-01 Dimensions	TID #: .TID		
PLOT NAME = Fabrication Drawing	GENERATED : 7/21/2015 4:29:41 PM	TEXAS INSTRUMENTS	

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ENGINEER: Wenjia Liu	LAYOUT BY: Who did the Layout?
SCALE: 1.00	ALTUM DESIGNER VERSION: 10.0.0.27009

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